OSTRICON™

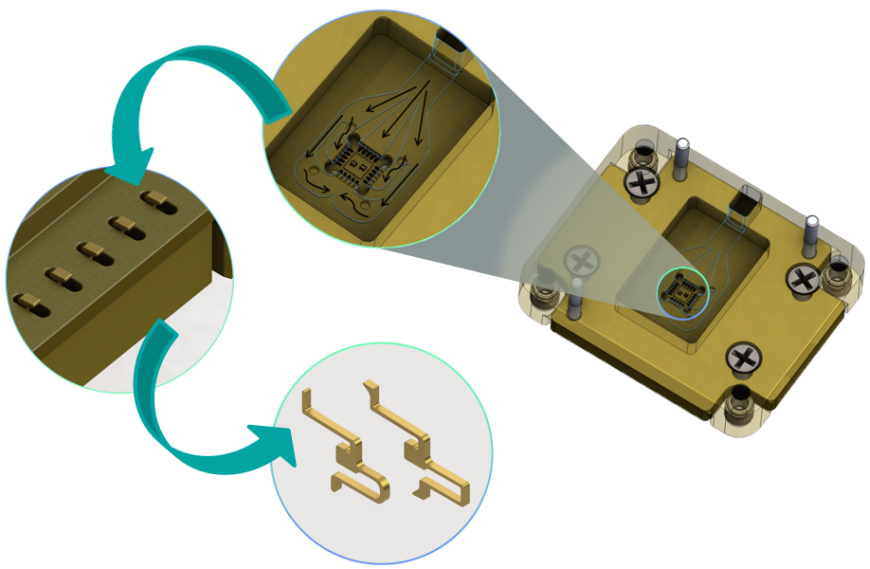
TEST CONTACTING SOLUTION

FOR TRI-TEMPERATURE TESTING WITH TCC CAPABILITIES

Ostricon is a unique cantilever style contacting solution which is designed for flexibility to match various loadboard footprints and test handler hardware. Ostricon contacting technology exhibits excellent Current Carrying Capacity (CCC) and low contact resistance which is ideal for mid to high power test requirements.

Ostricon test contacting solutions are available in Non-Kelvin configurations only for SOIC, TSOP, QFP, QFN etc. Leaded and Leadless style IC packages. Ostricon is also compatible to few of the existing solutions in the field.

Key Features	Ostricon Delivers
Cantilever Pins (Non-Kelvin)	Capable testing current up to 25A per pin Pulse & Voltage up to 7.5kV or more
Unique Pins Profile	Flexibility to match various loadboard footprint
Simplified and Flexible Housing Design	Less components and configurable for specific test requirements
Tri-Temperature	Thermal Conditioning Channel (TCC) design to maintain ± 2°C test temperature
Sustainable 1st Pass Yield (FPY)	Longer MTBA & MTBF
Loardboard Friendly	No mechanical movement & wearing on loadboard



Package Range : SOIC, SOP, MSOP, TSOP, QFP, DFN, QFN
Pitch : ≥ 0.4mm

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https://www.jf-technology.com

Design Features

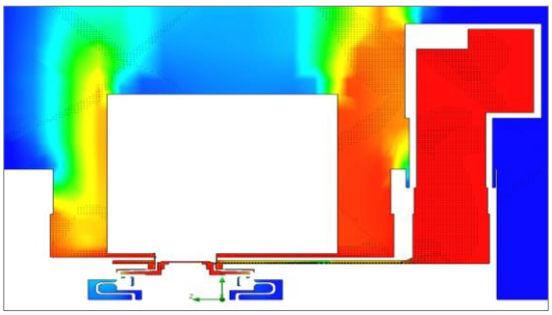
- ✓ Customizable Contact Tip Design & Bottom Profile
- ✓ Mechanical Robustness
- ✓ Advanced Contact Finishing (ACF)
- ✓ Thermal Conditional Channel (TCC) Technology
- ✓ Excellent Current Carrying Capacity (CCC)
- ✓ Versatile and Cost Effective

Electrical Specifications ①	Ostridge Tip	Round Tip
Electrical Length (mm)	8.87	8.51
Self Inductance (nH)	4.32	4.07
Resistance (mΩ)	≤ 25	≤ 25
Current Carrying Capacity (A) *Duty Cycle 100%, 75%, 50%, 25%, 1% (300ms)*	4.0 / 4.8 / 5.8 / 7.9 / 27.2	3.8 / 4.6 / 5.5 / 7.5 / 25.0
Current Leakage (pA) @ 10V	≤ 1.0	≤ 1.0

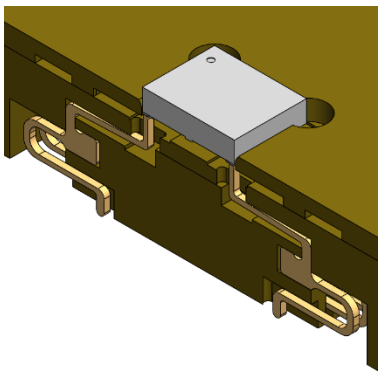
Mechanical Specifications	Ostridge Tip	Round Tip
Physical Pin Length (mm)	8.87	8.51
Pin Uncompressed Height (mm)	3.43	3.43
Pin Compliance (mm)	0.15	0.15
Pin Wiping Length (mm)	≤ 0.5	≤ 0.15
Gram Force per Pin (g)	35 ~ 45	20 ~ 40
Number of Insertion – Housing	≥ 6M	≥ 6M
Number of Insertion – Pin (Matte Tin)	≥ 500k	≥ 500k
Number of Insertion – Pin (NiPd)	≥ 300k	≥ 300k
Operating Temperature (°C)	- 60 to 180	- 60 to 180
Socket Material	Torlon® 5030 or equivalent	Torlon® 5030 or equivalent
Pin Material	BeCu - NiAu	BeCu - NiAu

① Results for 0.3mm thickness of pin

TCC Technology – Excellent thermal stability



Methodology



*Note * : The stated specifications are based on JF Microtechnology's Laboratory Test; the results may vary subjected to the test environment conditions. Information furnished by JF Microtechnology is believed to be accurate and reliable. However, no responsibility is assumed by JF Microtechnology for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of JF Microtechnology. Trademarks and registered trademarks are the property of their respective owners.*

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